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MOTOROLA
SEMICONDUCTOR
TECHNICAL DATA

MC145705
MC145706
MC145707

Product Preview

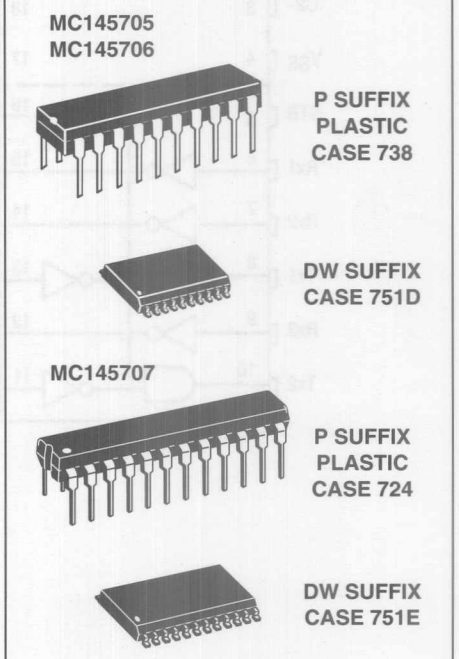
5-Volt-Only Driver/Receiver With an Integrated Standby Mode

EIA-232D and CCITT V.28

The MC145705/06/07 are a series of silicon-gate CMOS transceiver ICs that fulfill the electrical specifications of EIA-232D and CCITT V.28 while operating from a single +5 volt power supply. These transceiver series are high performance and low power consumption devices that are equipped with standby and output enable function.

A voltage doubler and inverter convert the +5 volts to ±10 volts. This is accomplished through an on-board 20 kHz oscillator and four inexpensive external electrolytic capacitors.

The MC145705 is composed of two drivers and three receivers, the MC145706 has three drivers and two receivers, and the MC145707 has three drivers and three receivers. These drivers and receivers are virtually identical to those of the MC145407.



Available Driver/Receiver Combinations

Device	Drivers	Receivers	No. of Pins
MC145705	2	3	20
MC145706	3	2	20
MC145707	3	3	24

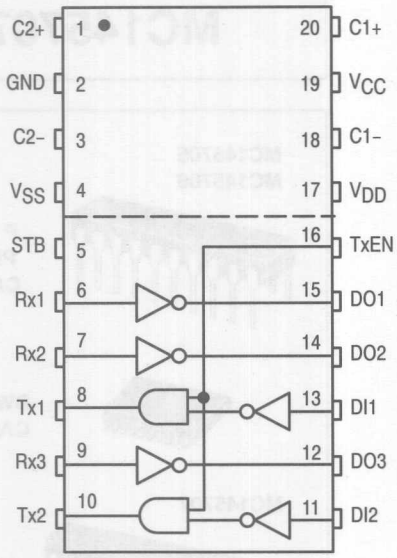
Drivers:
- ±7.5 Output Swing
- 300 Ω Power-Off Impedance
- Output Current Limiting
- TTL and CMOS Compatible Inputs
- Three-State Outputs During Standby Mode
- Hold Output OFF (MARK) State by TxEN Pin

Receivers:
- ±25 Volt Input Range
- 3 to 7 kΩ Input Impedance
- 0.8 V Hysteresis for Enhanced Noise Immunity
- Three-State Outputs During Standby Mode

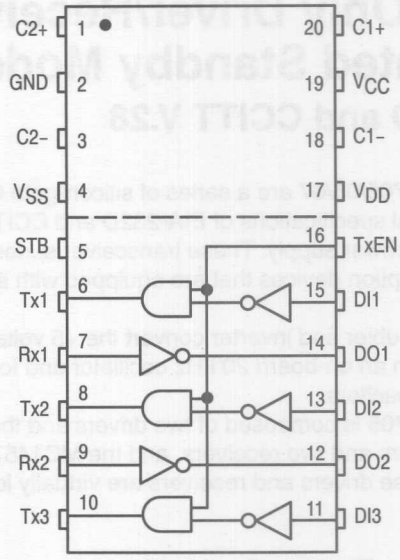
Charge Pumps:
- +5 to ±10 V Dual Charge Pump Architecture
- Supply Outputs Capable of Driving Three Drivers on the MC145403/06 Simultaneously
- Requires Four Inexpensive Electrolytic Capacitors
- On-Chip 20 kHz Oscillators

PIN ASSIGNMENTS

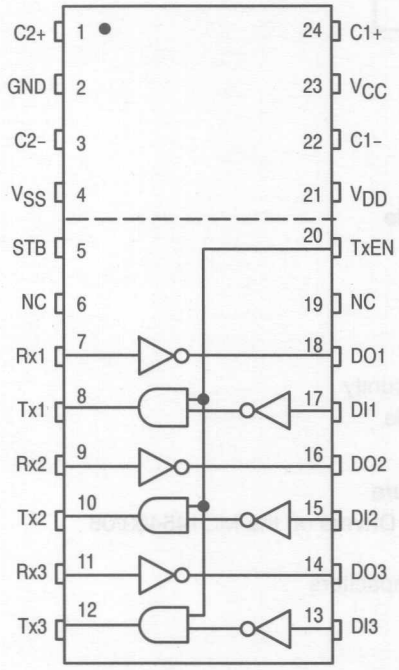
MC145705
2 Drivers/3 Receivers



MC145706
3 Drivers/2 Receivers

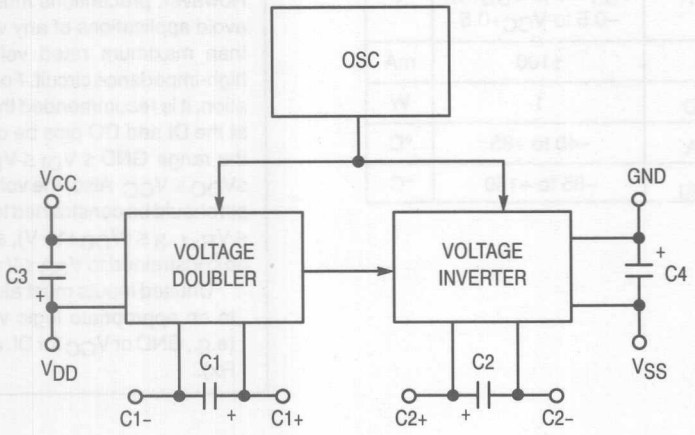


MC145707
3 Drivers/3 Receivers

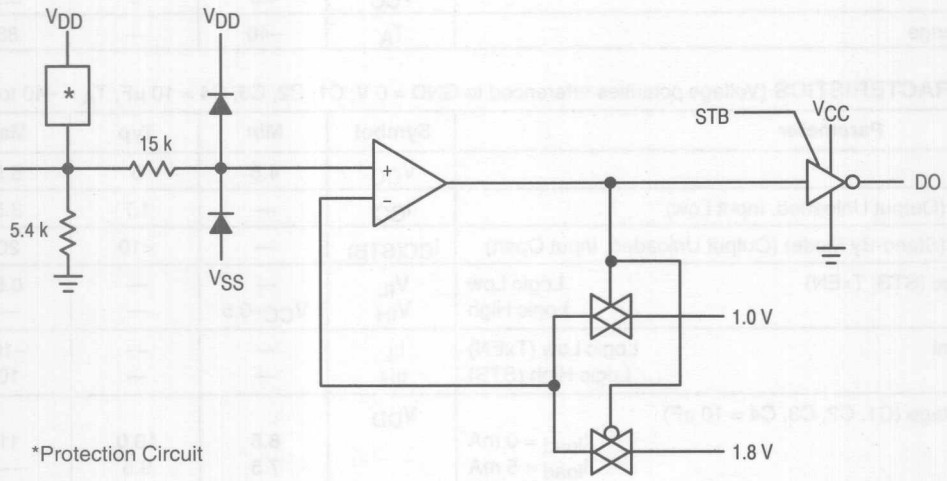


FUNCTION DIAGRAM

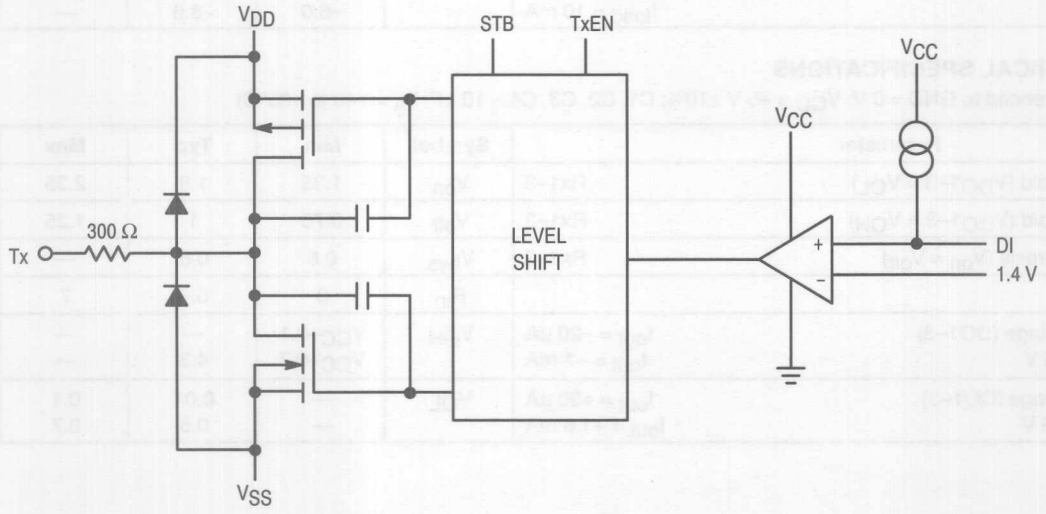
CHARGE PUMPS



RECEIVER



DRIVER



MAXIMUM RATINGS (Voltage Polarities Referenced to GND)

Rating		Symbol	Value	Unit
DC Supply Voltage		V_{CC}	–0.5 to +6.0	V
Input Voltage	Rx1–3 Inputs DI1–3 Inputs	V_{IR}	V_{SS}–15 to V_{DD}+15 –0.5 to V_{CC}+0.5	V
DC Current Per Pin		I	±100	mA
Power Dissipation		P_D	1	W
Operating Temperature Range		T_A	–40 to +85	°C
Storage Temperature Range		T_{stg}	–85 to +150	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, it is recommended that the voltage at the DI and DO pins be constrained to the range GND ≤ V_{DI} ≤ V_{DD} and GND ≤V_{DO} ≤ V_{CC}. Also, the voltage at the Rx pin should be constrained to (V_{SS}– 15 V) ≤ V_{Rx1-3} ≤ (V_{DD}+15 V), and Tx should be constrained to V_{SS} ≤ V_{Tx1-3} ≤ V_{DD}.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., GND or V_{CC} for DI, and GND for Rx).

RECOMMENDED OPERATING LIMITS

Parameter	Symbol	Min	Typ	Max	Unit
Power Supply	V_{CC}	4.5	5	5.5	V
Operating Temperature Range	T_A	–40	—	85	°C

DC ELECTRICAL CHARACTERISTICS (Voltage polarities referenced to GND = 0 V; C1, C2, C3, C4 = 10 µF; T_A = –40 to +85°C)

Parameter		Symbol	Min	Typ	Max	Unit
DC Power Supply		V_{CC}	4.5	5	5.5	V
Quiescent Supply Current (Output Unloaded, Input Low)		I_{CC}	—	1.7	3.5	mA
Quiescent Supply Current (Stand-By Mode) (Output Unloaded, Input Open)		$I_{CC(STB)}$	—	<10	20	µA
Control Signal Input Voltage (STB, TxEN)	Logic Low Logic High	V_{IL} V_{IH}	— V_{CC}–0.5	— —	0.5 —	V
Control Signal Input Current	Logic Low (TxEN) Logic High (STB)	I_{IL} I_{IH}	— —	— —	–10 10	µA
Charge Pumps Output Voltage (C1, C2, C3, C4 = 10 µF)		V_{DD}				V
Output Voltage (V_{DD})	I_{load} = 0 mA I_{load} = 5 mA I_{load} = 10 mA		8.5 7.5 6.0	10.0 9.5 9.0	11 — —	
Output Voltage (V_{SS})	I_{load} = 0 mA I_{load} = 5 mA I_{load} = 10 mA	V_{SS}	–8.5 –7.5 –6.0	–10.0 –9.2 –8.6	–11 — —	

RECEIVER ELECTRICAL SPECIFICATIONS

(Voltage polarities referenced to GND = 0 V; V_{CC} = +5 V ±10%; C1, C2, C3, C4 = 10 µF; T_A = –40 to +85°C)

Parameter		Symbol	Min	Typ	Max	Unit
Input Turn-On Threshold (V_{DO}1–3 = V_{OL})	Rx1–3	V_{on}	1.35	1.8	2.35	V
Input Turn-Off Threshold (V_{DO}1–3 = V_{OH})	Rx1–3	V_{off}	0.75	1	1.25	V
Input Threshold Hysteresis (V_{on} = V_{off})	Rx1–3	V_{hys}	0.6	0.8	—	V
Input Resistance		R_{in}	3	5.4	7	kΩ
High-Level Output Voltage (DO1–3) V_{Rx}1–3 = –3 to –25 V	I_{out} = –20 µA I_{out} = –1 mA	V_{OH}	V_{CC}–0.1 V_{CC}–0.7	— 4.3	— —	V
Low-Level Output Voltage (DO1–3) V_{Rx}1–3 = +3 to +25 V	I_{out} = +20 µA I_{out} = +1.6 mA	V_{OL}	— —	0.01 0.5	0.1 0.7	V

DRIVER ELECTRICAL SPECIFICATIONS

(Voltage polarities referenced to GND = 0 V; V_{CC} = +5 V ±10%; C1, C2, C3, C4 = 10 µF; T_A = –40 to +85°C)

Parameter		Symbol	Min	Typ	Max	Unit
Digital Input Voltage	DI1–3					V
Logic Low		V_{IL}	—	—	0.8	
Logic High		V_{IH}	2	—	—	
Input Current	DI1–3					µA
V_{DI} = GND		I_{IL}	—	7	—	
V_{DI} = V_{CC}		I_{IH}	—	—	±1.0	
Output High Voltage	Tx1–3	V_{OH}	6	7.5	—	V
($V_{DI1–3}$ = Logic Low, R_L = 3 kΩ)	Tx1–6*		5	6.5	—	
Output Low Voltage	Tx1–3	V_{OL}	–6	–7.5	—	V
($V_{DI1–3}$ = Logic High, R_L = 3 kΩ)	Tx1–6*		–5	–6.5	—	
Off Source Impedance	Tx1–3	Z_{off}	300	—	—	Ω
Output Short Circuit Current (V_{CC} = 5.5 V)		I_{SC}				mA
Tx1–3 Shorted to GND**			—	—	±60	
Tx1–3 Shorted to ±15 V***			—	—	±100	

* Specifications for a MC14570X powering a MC145406 or MC145403 with three additional drivers/receivers.

** Specification is for one Tx output to be shorted at a time. Should all three driver outputs be shorted simultaneously, device power dissipation limits could be exceeded.

*** This condition could exceed package limitations.

SWITCHING CHARACTERISTICS (V_{CC} = +5 V, ±10%; C1, C2, C3, C4 = 10 µF; T_A = –40 to +85°C)

Parameter		Symbol	Min	Typ	Max	Unit
Drivers						
Propagation Delay Time	Tx1–3					µs
Low-to-High (R_L = 3 kΩ, C_L = 50 pF or 2500 pF)		t_{PLH}	—	0.5	1	
High-to-Low (R_L = 3 kΩ, C_L = 50 pF or 2500 pF)		t_{PHL}	—	0.5	1	
Output Slew Rate	Tx1–3	SR				V/µs
Minimum Load R_L = 7 kΩ, C_L = 0 pF			—	±6	±30	
Maximum Load R_L = 3 kΩ, C_L = 2500 pF			—	±5	—	
Output Disable Time		t_{DAZ}	—	4	10	µs
Output Enable Time		t_{DZA}	—	25	50	ms
Receivers						
Propagation Delay Time	DO1–3					µs
Low-to-High		t_{PLH}	—	—	1	
High-to-Low		t_{PHL}	—	—	1	
Output Rise Time	DO1–3	t_r	—	250	400	ns
Output Fall Time	DO1–3	t_f	—	40	100	ns
Output Disable Time		t_{RAZ}	—	4	10	µs
Output Enable Time		t_{RZA}	—	25	50	ms

TRUTH TABLE

Drivers

DI	TxEN	STB	Tx
X	X	H	Z*
X	L	L	L
H	H	L	L
L	H	L	H

*$V_{SS} \le V_{Tx} \le V_{DD}$ X = Don't Care

Receivers

Rx	STB	DO
X	H	Z*
H	L	L
L	L	H

*GND ≤ V_{DO} ≤ V_{CC} X = Don't Care

PIN DESCRIPTIONS

V_{CC} — DIGITAL POWER SUPPLY

This digital supply pin is connected to the logic power supply. This pin should have a 0.33 µF capacitor to ground.

GND — GROUND

Ground return pin is typically connected to the signal ground pin of the EIA-232D connector (connector pin 7) as well as to the logic power supply ground.

V_{DD} — POSITIVE POWER SUPPLY

This is the positive output of the on-chip voltage doubler and the positive power supply input of the driver/receiver sections of the device. This pin requires an external storage capacitor to filter the 50% duty cycle voltage generated by the charge pump.

V_{SS} — NEGATIVE POWER SUPPLY

This is the negative output of the on-chip voltage doubler/inverter and the negative power supply input of the driver/receiver sections of the device. This pin requires an external storage capacitor to filter the 50% duty cycle voltage generated by the charge pump.

TxEN — OUTPUT ENABLE

This is the driver output enable pin. When this pin is in logic low level, the condition of the driver outputs (Tx1–3) are in keep OFF (mark) state.

STB — STAND-BY

The device enters the stand-by mode while this pin is connected to the logic high level. During the stand-by mode, driver and receiver output pins become high-impedance state. In this condition, supply current I_{CC} is below 10 µA (TYP) and can be operated with low current consumption.

C2+, C2–, C1+, C1– — VOLTAGE DOUBLER AND INVERTER

These are the connections to the internal voltage doubler and inverter, which generate the V_{DD} and V_{SS} voltages.

Rx1, Rx2 (Rx3) — RECEIVE DATA INPUT

These are the EIA-232D receive signal inputs. A voltage between +3 and +25 V is decoded as a space, and causes the corresponding DO pin to swing to ground (0 V). A voltage between –3 and –25 V is decoded as a mark, and causes the DO pin to swing up to V_{CC}.

DO1, DO2 (DO3) — DATA OUTPUT

These are the receiver digital output pins, which swing from V_{CC} to GND. Each output pin is capable of driving one LSTTL input load.

Output level of these pins is high-impedance while in stand-by mode.

DI1, DI2 (DI3) — DATA INPUT

These are the high-impedance digital input pins to the drivers. Input voltage levels on these pins must be between V_{CC} and GND.

The level of these input pins are TTL/CMOS compatible.

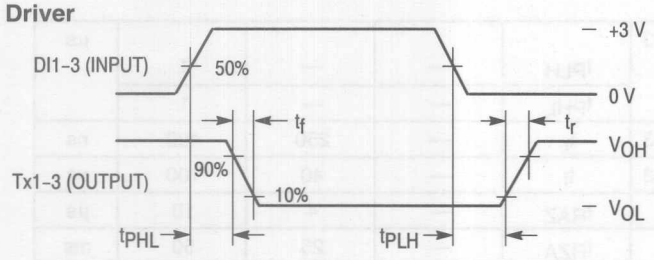
Tx1, Tx2 (Tx3) — TRANSMIT DATA OUTPUT

These are the EIA-232D transmit signal output pins, which swing toward V_{DD} and V_{SS}. A logic one at a DI input causes the corresponding Tx output to swing toward V_{SS}. The actual levels and slew rate achieved will depend on the output loading (RL/CL).

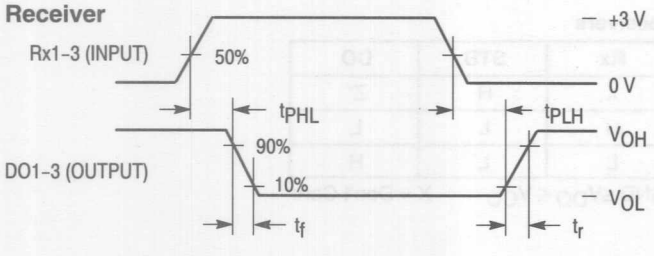
The minimum output impedance is 300 Ω when turned off.

SWITCHING CHARACTERISTICS

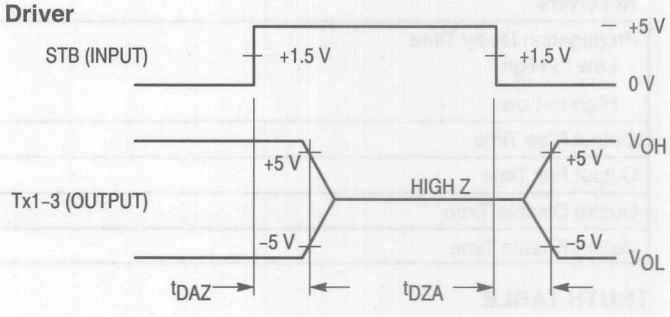
Driver



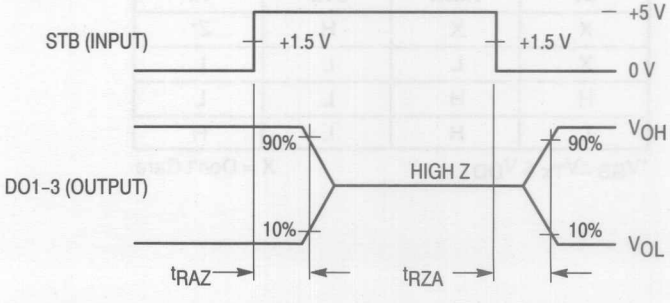
Receiver



Driver

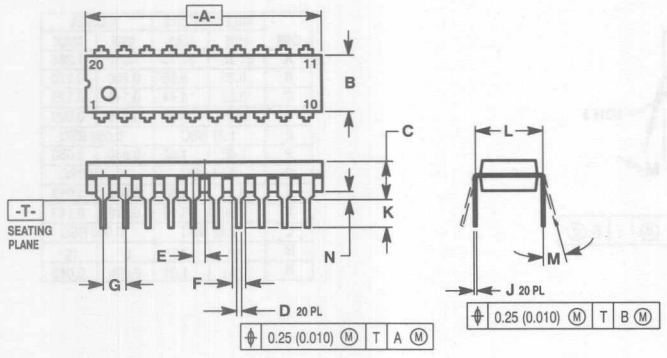


Receiver



PACKAGE DIMENSIONS

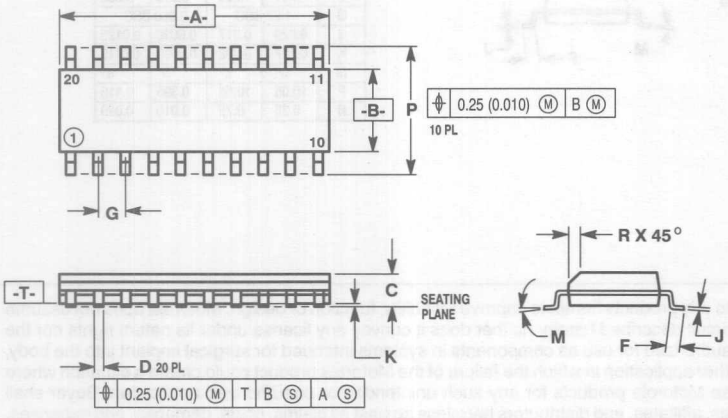
MC145705/06
P SUFFIX
PLASTIC
CASE 738-03



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION "L" TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	25.66	27.17	1.010	1.070
B	6.10	6.60	0.240	0.260
C	3.81	4.57	0.150	0.180
D	0.39	0.55	0.015	0.022
E	1.27 BSC		0.050 BSC	
F	1.27	1.77	0.050	0.070
G	2.54 BSC		0.100 BSC	
J	0.21	0.38	0.008	0.015
K	2.80	3.55	0.110	0.140
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

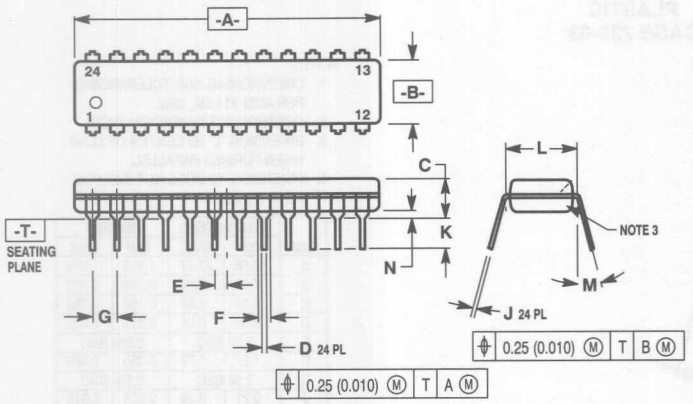
MC145705/06
DW SUFFIX
CASE 751D-03



NOTES:
1. DIMENSIONS A AND B ARE DATUMS AND T IS A DATUM SURFACE.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
3. CONTROLLING DIMENSION: MILLIMETER.
4. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

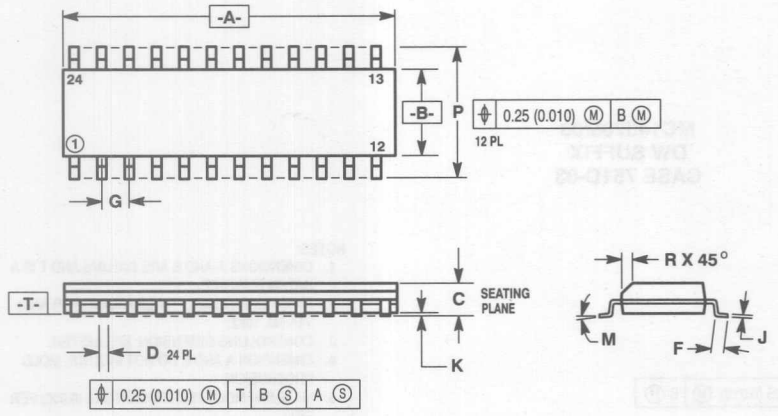
MC145707
P SUFFIX
PLASTIC
CASE 724-03



NOTES:
1. CHAMFERRED CONTOUR OPTIONAL.
2. DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.
4. CONTROLLING DIMENSION: INCH.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	31.25	32.13	1.230	1.265
B	6.35	6.85	0.250	0.270
C	3.69	4.44	0.145	0.175
D	0.38	0.51	0.015	0.020
E	1.27 BSC		0.050 BSC	
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
J	0.18	0.30	0.007	0.012
K	2.80	3.55	0.110	0.140
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

MC145707
DW SUFFIX
CASE 751E-03



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2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
3. CONTROLLING DIMENSION: MILLIMETER.
4. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	15.25	15.54	0.601	0.612
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.229	0.317	0.0090	0.0125
K	0.127	0.292	0.0050	0.0115
M	0°	8°	0°	8°
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

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